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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

High Speed Infrared Emitting Diode, 940 nm, GaAlAs Double Hetero

21531

FEATURES

- Package type: surface mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- AEC-Q101 qualified
- Enhanced operating temperature range: -40 °C to +105 °C
- Peak wavelength: λ_p = 940 nm
- High reliability
- High radiant power
- High radiant intensity
- High speed
- Angle of half sensitivity: φ = ± 60°
- Low forward voltage
- Suitable for high pulse current operation
- 0805 standard surface-mountable package
- Floor life: 72 h, MSL 4, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE

Pb-free

e4

RoHS COMPLIANT

HALOGEN FREE

GREEN (5-2008)

DESCRIPTION

VSMB1940ITX01 is an infrared, 940 nm emitting diode in GaAlAs double hetero technology with high radiant power and high speed, molded in clear, untinted 0805 plastic package for surface mounting (SMD).

APPLICATIONS

- IR emitter for automotive applications
- High power emitter for low space applications
- High performance transmissive or reflective sensors

PRODUCT SUMMARY

COMPONENT	I_e (mW/sr)	φ (deg)	λ_p (nm)	t_r (ns)
VSMB1940ITX01	6	± 60	940	15

Note

- Test conditions see table “Basic Characteristics“

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMB1940ITX01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25 °C, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	t_p/T = 0.5, t_p = 100 µs	I_{FM}	200	mA
Surge forward current	t_p = 100 µs	I_{FSM}	1	A
Power dissipation		P_V	160	mW
Junction temperature		T_j	110	°C
Operating temperature range		T_{amb}	-40 to +105	°C
Storage temperature range		T_{stg}	-40 to +110	°C
Soldering temperature	According to reflow profile Fig. 9	T_{sd}	260	°C
Thermal resistance junction / ambient	JESD 51	R_{thJA}	270	K/W

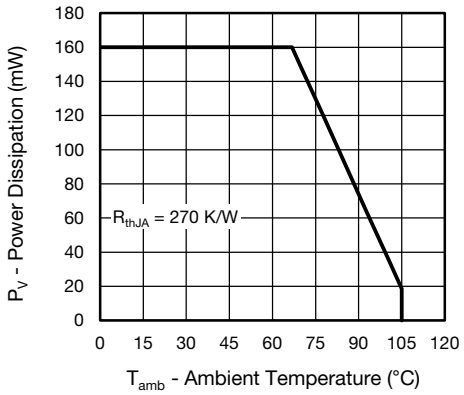


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

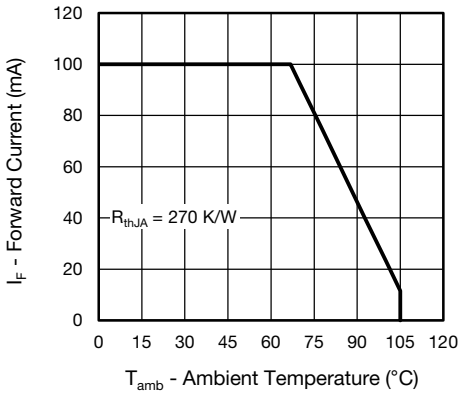


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Forward voltage	I_F = 100 mA, t_p = 20 ms	V_F	1.15	1.35	1.6	V
	I_F = 1 A, t_p = 100 µs	V_F	-	2.2	-	V
Temperature coefficient of V_F	I_F = 1 mA	TK_{VF}	-	-1.5	-	mV/K
	I_F = 100 mA	TK_{VF}	-	-1.1	-	mV/K
Reverse current	V_R = 5 V	I_R	-	-	10	µA
Junction capacitance	V_R = 0 V, f = 1 MHz, E = 0 mW/cm^2	C_J	-	70	-	pF
Radiant intensity	I_F = 100 mA, t_p = 20 ms	I_e	3	6	12	mW/sr
	I_F = 1 A, t_p = 100 µs	I_e	-	60	-	mW/sr
Radiant power	I_F = 100 mA, t_p = 20 ms	ϕe	-	40	-	mW
Temperature coefficient of radiant power	I_F = 1 mA	$TK\phi_e$	-	-1.1	-	%/K
	I_F = 100 mA	$TK\phi_e$	-	-0.51	-	%/K
Angle of half intensity		φ	-	± 60	-	deg
Peak wavelength	I_F = 30 mA	λ_p	-	940	-	nm
Spectral bandwidth	I_F = 30 mA	$\Delta\lambda$	-	25	-	nm
Temperature coefficient of λ_p	I_F = 30 mA	$TK_{\lambda p}$	-	0.25	-	nm
Rise time	I_F = 100 mA, 20 % to 80 %	t_r	-	15	-	ns
Fall time	I_F = 100 mA, 20 % to 80 %	t_f	-	15	-	ns
Virtual source diameter		d	-	0.5	-	mm

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

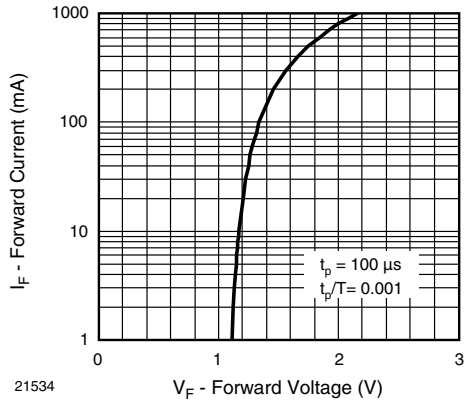


Fig. 3 - Forward Current vs. Forward Voltage

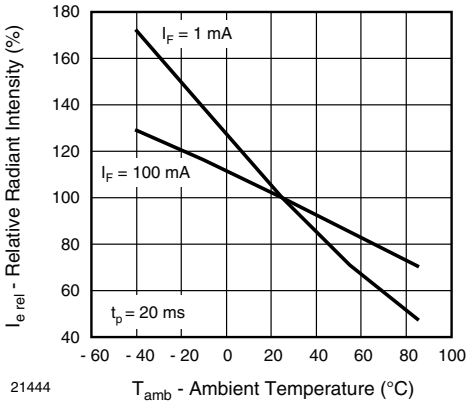


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

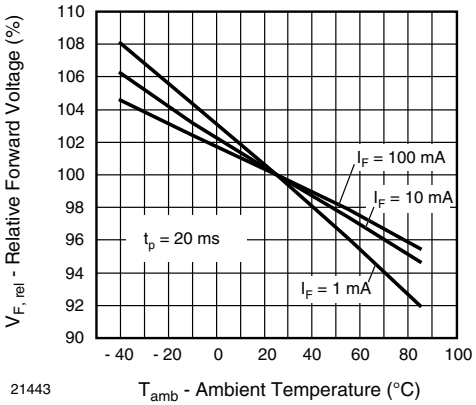


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

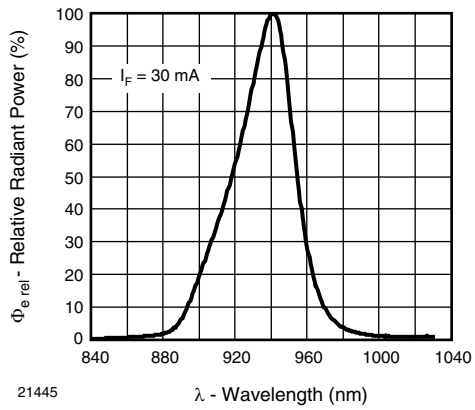


Fig. 7 - Relative Radiant Power vs. Wavelength

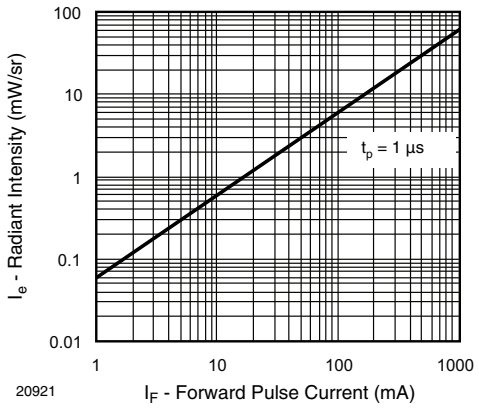


Fig. 5 - Radiant Intensity vs. Forward Current

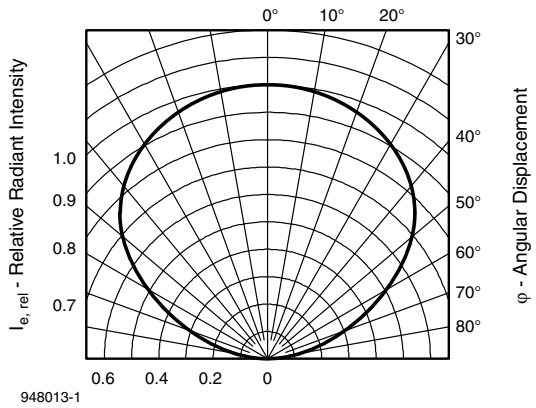


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

REFLOW SOLDER PROFIEL

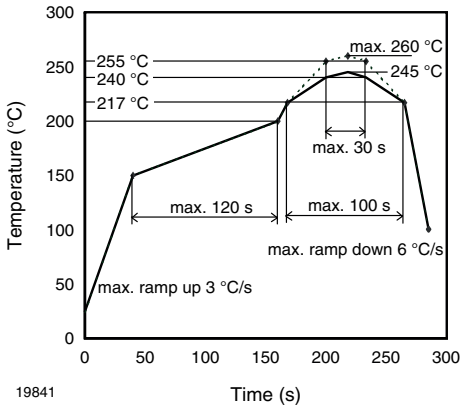


Fig. 9 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 4

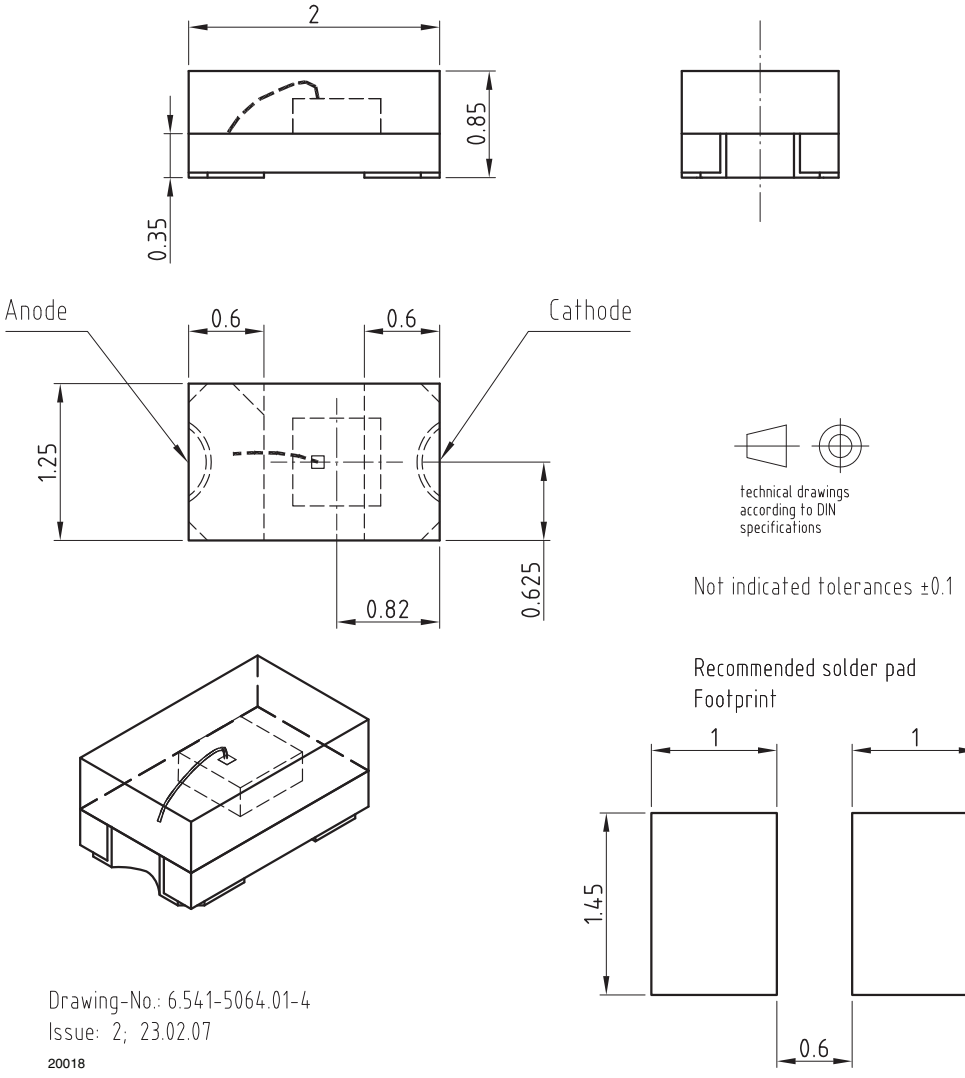
Floor life: 72 h

Conditions: T_{amb} < 30 °C, RH < 60 %

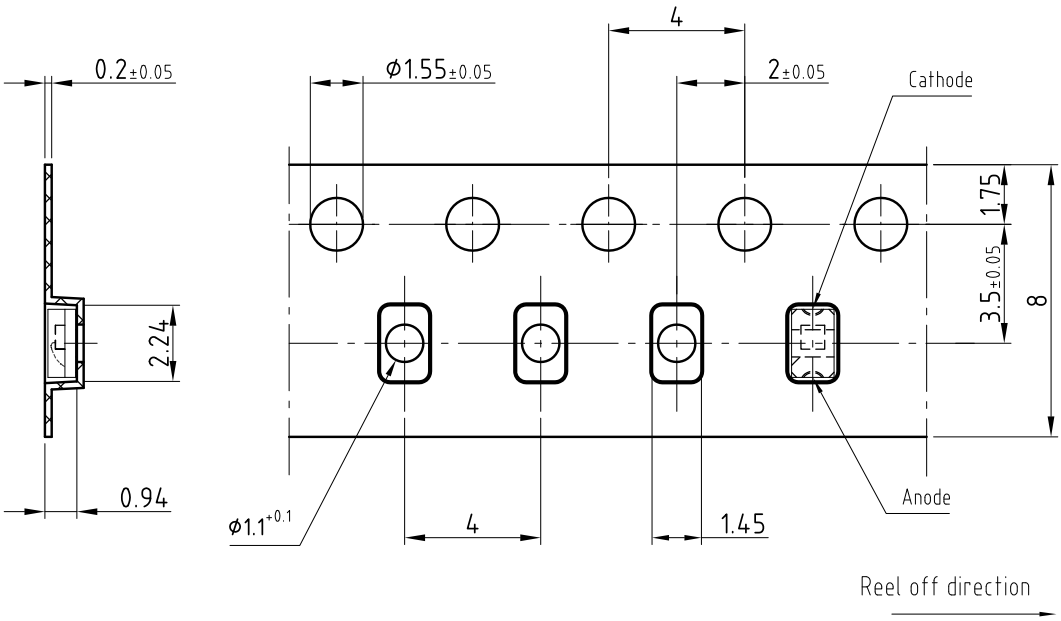
DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

PACKAGE DIMENSIONS in millimeters



BLISTER TAPE DIMENSIONS in millimeters

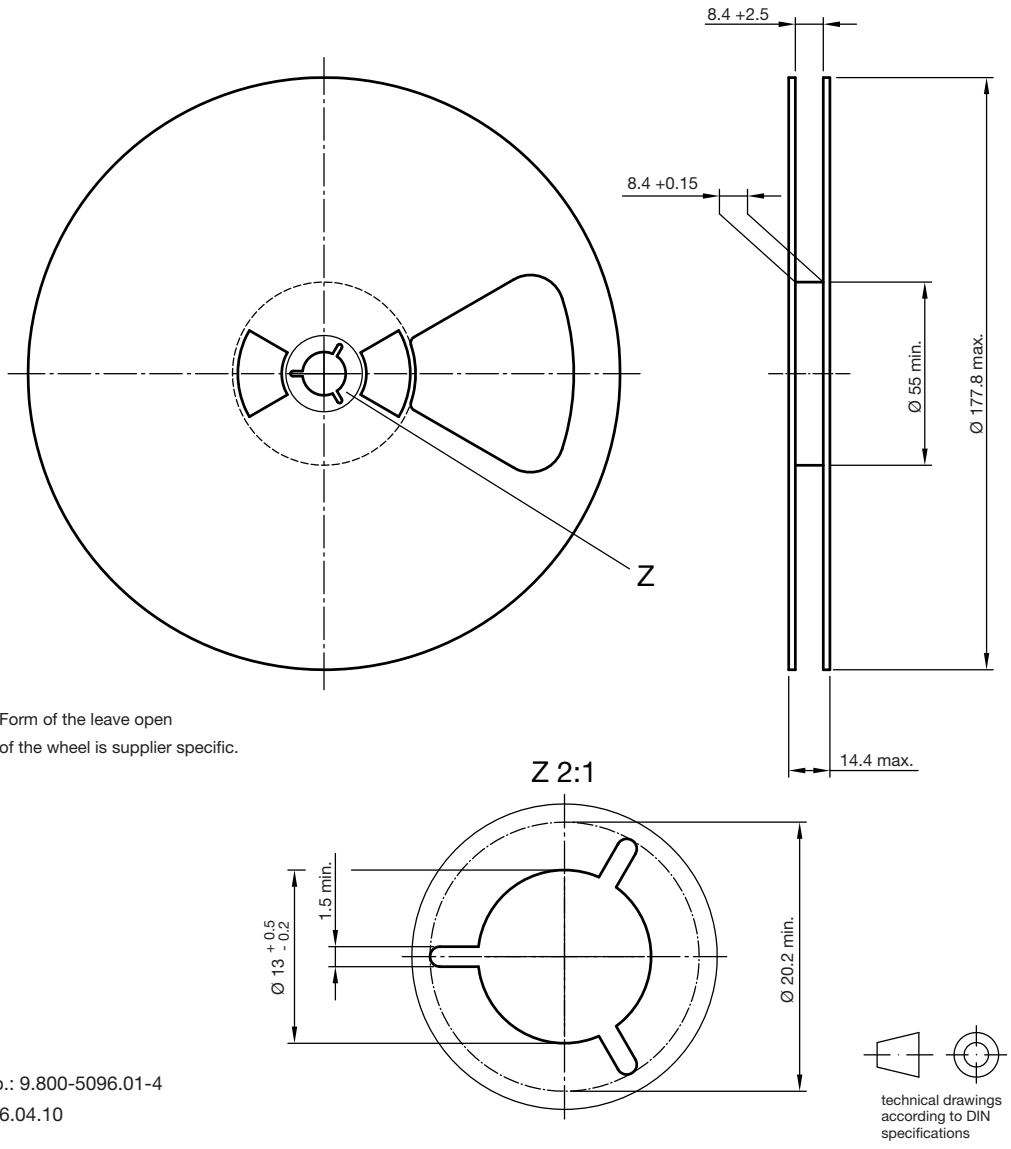


technical drawings
according to DIN
specifications

Drawing-No.: 9.700-5311.01-4
Issue: 1; 23.02.07
21501

Not indicated tolerances ±0.1

REEL DIMENSIONS in millimeters



Form of the leave open
of the wheel is supplier specific.

technical drawings
according to DIN
specifications

Drawing-No.: 9.800-5096.01-4
Issue: 2; 26.04.10
20875

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